



Material Composition Declaration

EPC2215

Company Name	Efficient Power Conversion (EPC)	Issue Date:	4/24/2024
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	9.9 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	8.4915	86.1392	89.7782	861392
	Silicon oxide	7631-86-9	0.0573	0.5809		5809
	Silicon nitride	12033-89-5	0.0189	0.1916		1916
	Gallium nitride	25617-97-4	0.0672	0.6819		6819
	Aluminum	7429-90-5	0.0982	0.9959		9959
	Aluminum nitride	24304-00-5	0.0138	0.1398		1398
	Titanium	7440-32-6	0.0020	0.0199		199
	Titanium nitride	25583-20-4	0.0123	0.1250		1250
	Copper	7440-50-8	0.0016	0.0166		166
	Tungsten	7440-33-7	0.0069	0.0700		700
	Polyimide		0.0806	0.8173	8173	
Under Bump Metal	Titanium	7440-32-6	0.0008	0.0079	0.0864	79
	Copper	7440-50-8	0.0077	0.0785		785
Solder Bump	Copper	7440-50-8	0.0774	0.7852	10.1354	7852
	Nickel	7440-02-0	0.0462	0.4684		4684
	Tin	7440-31-5	0.8598	8.7220		87220
	Silver	7440-22-4	0.0158	0.1599		1599
Sum in total:			9.8579	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.